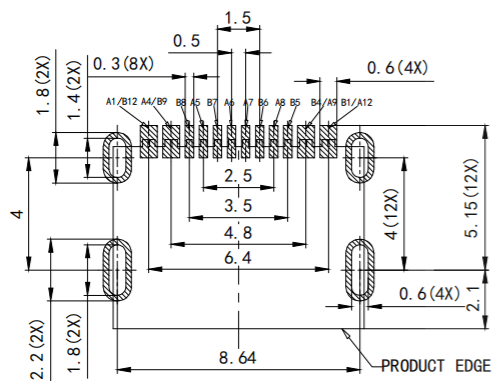
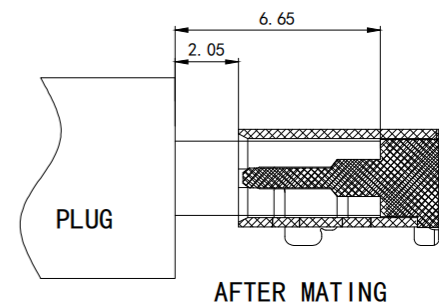
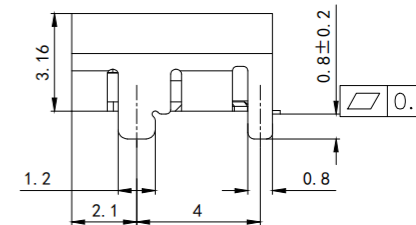
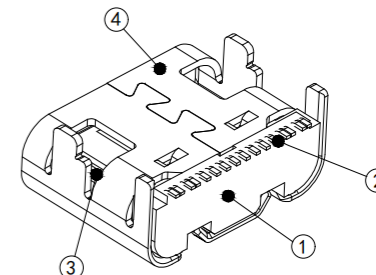
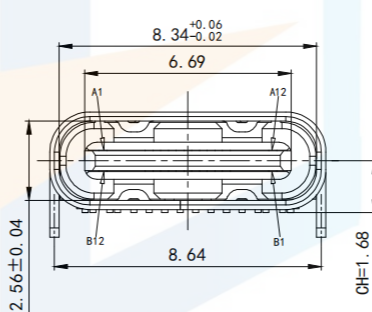
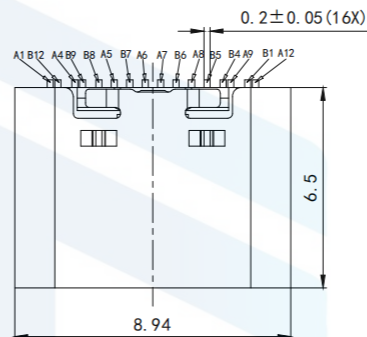
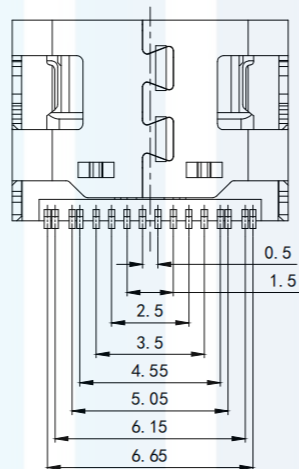


RoHS2.0
Compliant

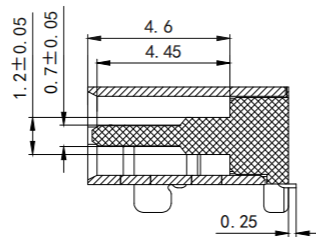


RECOMMENDED PCB LAYOUT (TOP VIEW)
THICKNESS 0.6MM DEFAULT TOLERANCE ± 0.05



NOTE:

1. MATERIAL SPECIFICATION:
 1. HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC LCP BK, UL94 V-0.
 2. CONTACTS: COPPER ALLOY C1814
 3. MID PLATE: STAINLESS STEEL SUS301
 4. FRONT SHELL: STAINLESS STEEL SUS304
2. PLATING SPECIFICATION:
 - 2-1. CONTACTS: Ni 50U" MIN. UNDER PLATED OVER ALL.
AU PLATED ON THE FUNCTIONAL AREA OF CONTACT
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 - 2-2. FRONT SHELL:
Ni 30U" MIN. UNDER PLATED OVER ALL
 - 2-3. MID PLATE:
CLEAR ONLY
3. MECHANICAL PERFORMANCE:
 - 3-1. INSERTION FORCE: 0.5~2.0 Dkgf.
 - 3-2. REMOVAL FORCE: 0.8kgf~2.0kgf.
 - 3-3. DURABILITY: 10000 CYCLES.
4. ELECTRICAL PERFORMANCE:
 - 4-1. CURRENT RATING: 5.0A
VOLTAGE RATING: 5.0V
 - 4-2. LLGR:
VBUS & GND PINS AND OTHER PINS: 40m2/PIN MAX.
SHIELD: 50m2/MAXLLGR MAX.
CHANGE OF ALL PINS: 10mm.
 - 4-3. INSULATION RESISTANCE: 100M2 MIN
 - 4-4. DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE
5. ENVIRONMENTAL PERFORMANCE: OPERATING TEMPERATURE: -25°C~+85°C
6. IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

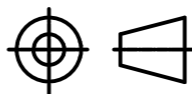


SECTION A-A
SCALE 1:1

TOLERANCE

| | |
|--------|-----------------|
| X. XXX | ± 0.05 |
| X. XX | ± 0.15 |
| X. X | ± 0.20 |
| X. | ± 0.30 |
| ANGLE | $\pm 5.0^\circ$ |

PROTECTON



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<https://www.hq-dz.com>

phone: 15812872448

TITLE:

TYPE C 16P板上端子SMT
4定位脚插板L=6.5

PART NO: TYPE-C16P-BS065

DRAWING NO: 8.94*6.5*3.16

DRAWN:

CHECKED:

APPROVED:

DATE:

DATE:

DATE:

18-10-08

18-10-08

18-10-08

UNIT:
mm
SCALE:
FULL
SIZE:
A4